



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	97
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp6e-3tn144c

Features

■ Extensive Density and Package Options

- 1.5K to 32.8K LUT4s
- 65 to 496 I/Os
- Density migration supported

■ sysDSP™ Block (LatticeECP™ Versions)

- High performance multiply and accumulate
- 4 to 8 blocks
 - 4 to 8 36x36 multipliers or
 - 16 to 32 18x18 multipliers or
 - 32 to 64 9x9 multipliers

■ Embedded and Distributed Memory

- 18 Kbits to 498 Kbits sysMEM™ Embedded Block RAM (EBR)
- Up to 131 Kbits distributed RAM
- Flexible memory resources:
 - Distributed and block memory

■ Flexible I/O Buffer

- Programmable sysI/O™ buffer supports wide range of interfaces:

- LVCMOS 3.3/2.5/1.8/1.5/1.2
- LVTTTL
- SSTL 3/2 Class I, II, SSTL18 Class I
- HSTL 18 Class I, II, III, HSTL15 Class I, III
- PCI
- LVDS, Bus-LVDS, LVPECL, RSDS

■ Dedicated DDR Memory Support

- Implements interface up to DDR400 (200MHz)

■ sysCLOCK™ PLLs

- Up to four analog PLLs per device
- Clock multiply, divide and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
- SPI boot flash interface
- 1.2V power supply

■ Low Cost FPGA

- Features optimized for mainstream applications
- Low cost TQFP and PQFP packaging

Table 1-1. LatticeECP/EC Family Selection Guide

Device	LFEC1	LFEC3	LFEC6/ LFCEP6	LFEC10/ LFCEP10	LFEC15/ LFCEP15	LFEC20/ LFCEP20	LFEC33/ LFCEP33
PFU/PFF Rows	12	16	24	32	40	44	64
PFU/PFF Columns	16	24	32	40	48	56	64
PFUs/PFFs	192	384	768	1280	1920	2464	4096
LUTs (K)	1.5	3.1	6.1	10.2	15.4	19.7	32.8
Distributed RAM (Kbits)	6	12	25	41	61	79	131
EBR SRAM (Kbits)	18	55	92	276	350	424	498
EBR SRAM Blocks	2	6	10	30	38	46	54
sysDSP Blocks ¹	—	—	4	5	6	7	8
18x18 Multipliers ¹	—	—	16	20	24	28	32
V _{CC} Voltage (V)	1.2	1.2	1.2	1.2	1.2	1.2	1.2
Number of PLLs	2	2	2	4	4	4	4
Packages and I/O Combinations:							
100-pin TQFP (14 x 14 mm)	67	67					
144-pin TQFP (20 x 20 mm)	97	97	97				
208-pin PQFP (28 x 28 mm)	112	145	147	147			
256-ball fpBGA (17 x 17 mm)		160	195	195	195		
484-ball fpBGA (23 x 23 mm)			224	288	352	360	360
672-ball fpBGA (27 x 27 mm)						400	496

1. LatticeECP devices only.

Table 2-7. Maximum Number of Elements in a Block

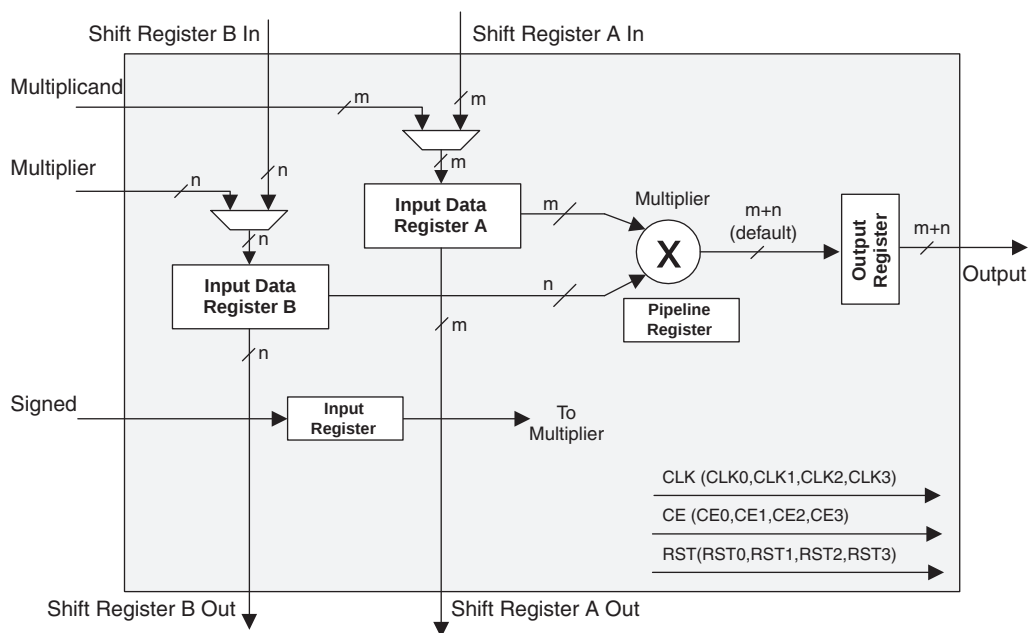
Width of Multiply	x9	x18	x36
MULT	8	4	1
MAC	2	2	—
MULTADD	4	2	—
MULTADDSUM	2	1	—

Some options are available in four elements. The input register in all the elements can be directly loaded or can be loaded as shift registers from previous operand registers. In addition by selecting “dynamic operation” in the ‘Signed/Unsigned’ options the operands can be switched between signed and unsigned on every cycle. Similarly by selecting ‘Dynamic operation’ in the ‘Add/Sub’ option the Accumulator can be switched between addition and subtraction on every cycle.

MULT sysDSP Element

This multiplier element implements a multiply with no addition or accumulator nodes. The two operands, A and B, are multiplied and the result is available at the output. The user can enable the input/output and pipeline registers. Figure 2-19 shows the MULT sysDSP element.

Figure 2-19. MULT sysDSP Element



MAC sysDSP Element

In this case the two operands, A and B, are multiplied and the result is added with the previous accumulated value. This accumulated value is available at the output. The user can enable the input and pipeline registers but the output register is always enabled. The output register is used to store the accumulated value. A registered overflow signal is also available. The overflow conditions are provided later in this document. Figure 2-20 shows the MAC sysDSP element.

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeECP/EC family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysI/O Buffer

Each I/O is associated with a flexible buffer referred to as a sysI/O buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysI/O buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysI/O Buffer Banks

LatticeECP/EC devices have eight sysI/O buffer banks; each is capable of supporting multiple I/O standards. Each sysI/O bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-34 shows the eight banks and their associated supplies.

In the LatticeECP/EC devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using V_{CCIO} . LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as fixed threshold input independent of V_{CCIO} . In addition to the bank V_{CCIO} supplies, the LatticeECP/EC devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeECP/EC devices, some dedicated I/O pins in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other V_{CCIO} banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. For more information about controlling the output logic state with valid input logic levels during power-up in LatticeECP/EC devices, see the list of technical documentation at the end of this data sheet.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric. V_{CCIO} supplies should be powered-up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The LatticeECP/EC sysI/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, RSDS, differential SSTL and differential HSTL. Tables 2-13 and 2-14 show the I/O standards (together with their supply and reference voltages) supported by the LatticeECP/EC devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V_{REF} (Nom.)	V_{CCIO}^1 (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVCMOS33 ²	—	—
LVCMOS25 ²	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12 ²	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
Differential Interfaces		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL, BLVDS, RSDS	—	—

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.

2. JTAG inputs do not have a fixed threshold option and always follow V_{CCJ} .

Oscillator

Every LatticeECP/EC device has an internal CMOS oscillator which is used to derive a master clock for configuration. The oscillator and the master clock run continuously. The default value of the master clock is 2.5MHz. Table 2-15 lists all the available Master Clock frequencies. When a different Master Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Clock frequency.
2. During configuration the device starts with the default (2.5MHz) Master Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information about the use of this oscillator for configuration, please see the list of technical documentation at the end of this data sheet.

Table 2-15. Selectable Master Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5*	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

Density Shifting

The LatticeECP/EC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

RSDS

The LatticeECP/EC devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

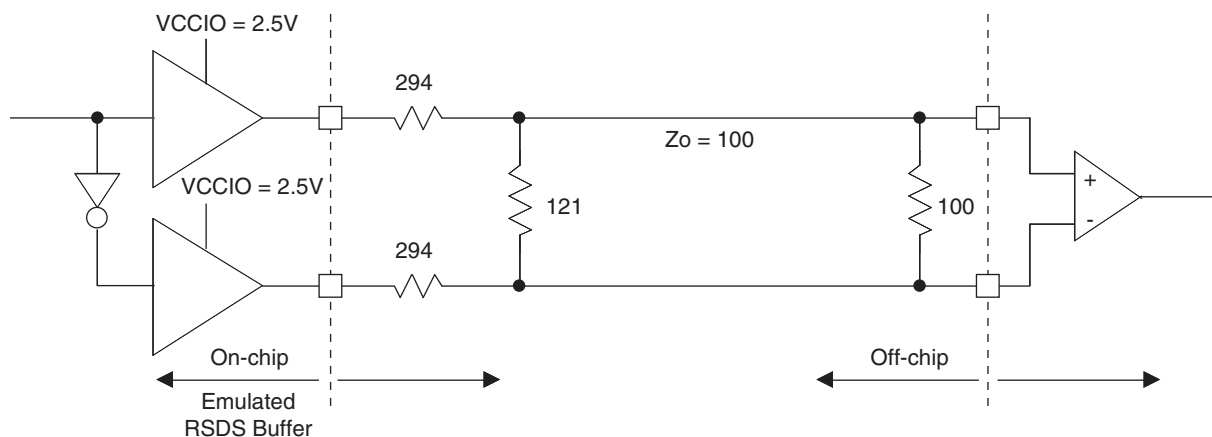
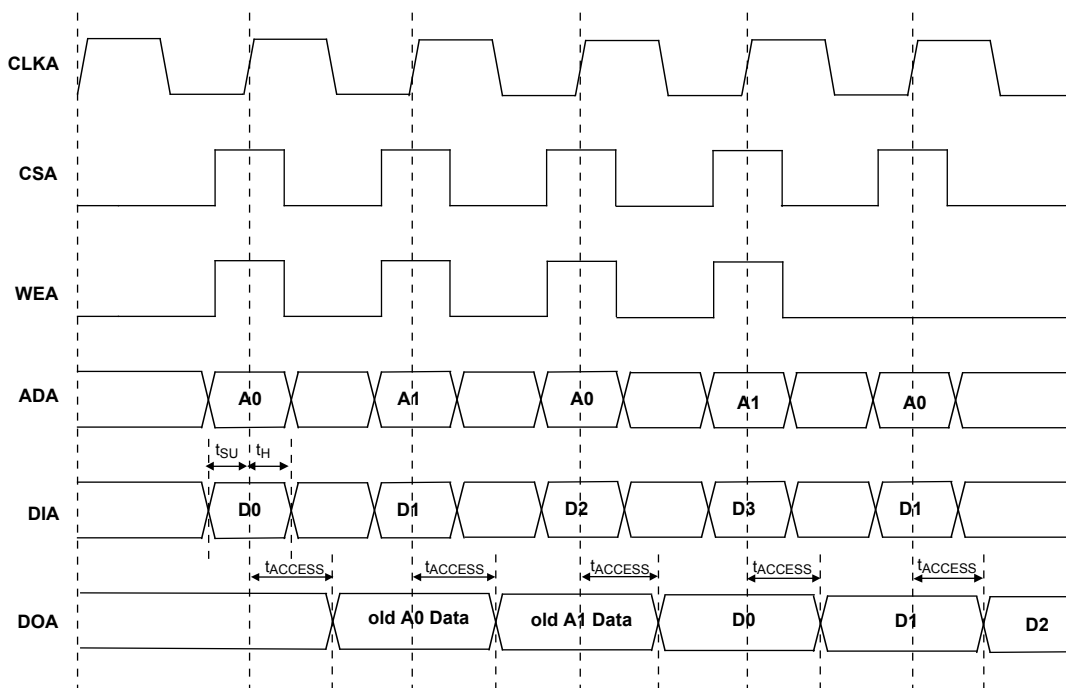


Table 3-4. RSDS DC Conditions

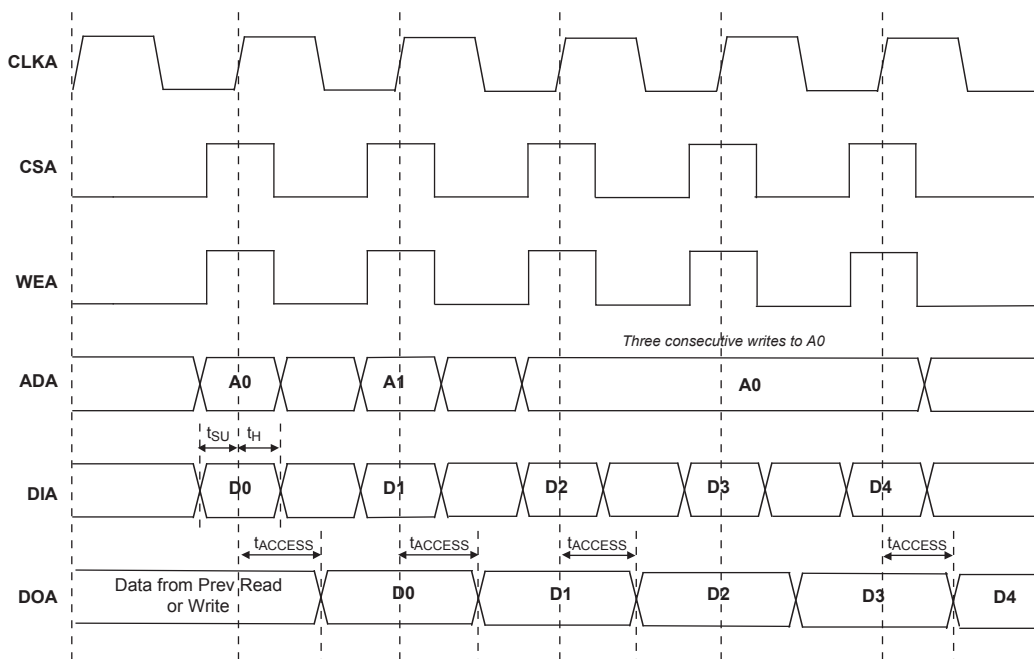
Parameter	Description	Typical	Units
Z _{OUT}	Output impedance	20	ohm
R _S	Driver series resistor	294	ohm
R _P	Driver parallel resistor	121	ohm
R _T	Receiver termination	100	ohm
V _{OH}	Output high voltage	1.35	V
V _{OL}	Output low voltage	1.15	V
V _{OD}	Output differential voltage	0.20	V
V _{CM}	Output common mode voltage	1.25	V
Z _{BACK}	Back impedance	101.5	ohm
I _{DC}	DC output current	3.66	mA

Figure 3-10. Read Before Write (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

Figure 3-11. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

LatticeECP/EC Family Timing Adders^{1, 2, 3} (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_II	HSTL_15 class II	0.10	0.12	0.14	ns
HSTL15_III	HSTL_15 class III	0.10	0.12	0.14	ns
HSTL15D_I	Differential HSTL 15 class I	0.08	0.10	0.11	ns
HSTL15D_III	Differential HSTL 15 class III	0.10	0.12	0.14	ns
SSTL33_I	SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33_II	SSTL_3 class II	0.40	0.48	0.56	ns
SSTL33D_I	Differential SSTL_3 class I	-0.05	-0.06	-0.07	ns
SSTL33D_II	Differential SSTL_3 class II	0.40	0.48	0.56	ns
SSTL25_I	SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25_II	SSTL_2 class II	0.25	0.30	0.35	ns
SSTL25D_I	Differential SSTL_2 class I	0.05	0.07	0.08	ns
SSTL25D_II	Differential SSTL_2 class II	0.25	0.30	0.35	ns
SSTL18_I	SSTL_1.8 class I	0.01	0.01	0.01	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.01	0.01	0.01	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.09	0.11	0.13	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.07	0.08	0.09	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.03	-0.04	-0.05	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.36	0.43	0.51	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.28	0.33	0.39	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.09	0.11	0.13	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.07	0.08	0.09	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.03	-0.04	-0.05	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.36	0.43	0.51	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.28	0.33	0.39	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.18	0.21	0.25	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.14	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.22	0.26	0.31	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.14	0.16	0.19	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.15	0.18	0.21	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.06	0.08	0.09	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.01	0.01	0.01	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.16	0.19	0.22	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.26	0.31	0.36	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.04	0.04	0.05	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.36	0.43	0.50	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.08	0.10	0.11	ns
LVC MOS12_4mA	LVC MOS 1.2 4mA drive	0.36	0.43	0.50	ns
PCI33	PCI33	1.05	1.26	1.46	ns

1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing measured with the load specified in Switching Test Conditions table of this document.

3. All other standards according to the appropriate specification.

Timing v.G 0.30

sysCLOCK PLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	—	420	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	—	420	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	—	210	MHz
f_{VCO}	PLL VCO Frequency		420	—	840	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	—	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default Duty Cycle Elected ³	45	50	55	%
t_{PH}^4	Output Phase Accuracy		—	—	0.05	UI
t_{OPJIT}^1	Output Clock Period Jitter	$f_{OUT} \geq 100\text{MHz}$	—	—	+/- 125	ps
		$f_{OUT} < 100\text{MHz}$	—	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	—	+/- 200	ps
t_W	Output Clock Pulse Width	At 90% or 10% ³	1	—	—	ns
t_{LOCK}^2	PLL Lock-in Time		—	—	150	μs
t_{PA}	Programmable Delay Unit		100	250	450	ps
t_{IPJIT}	Input Clock Period Jitter		—	—	+/- 200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width		10	—	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. Relative to CLKOP.

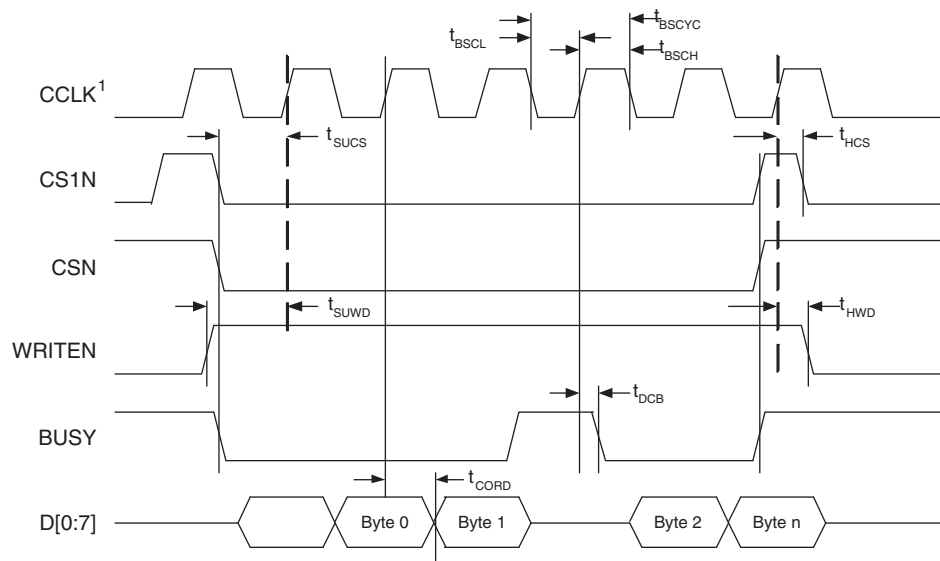
Timing v.G 0.30

LatticeECP/EC sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

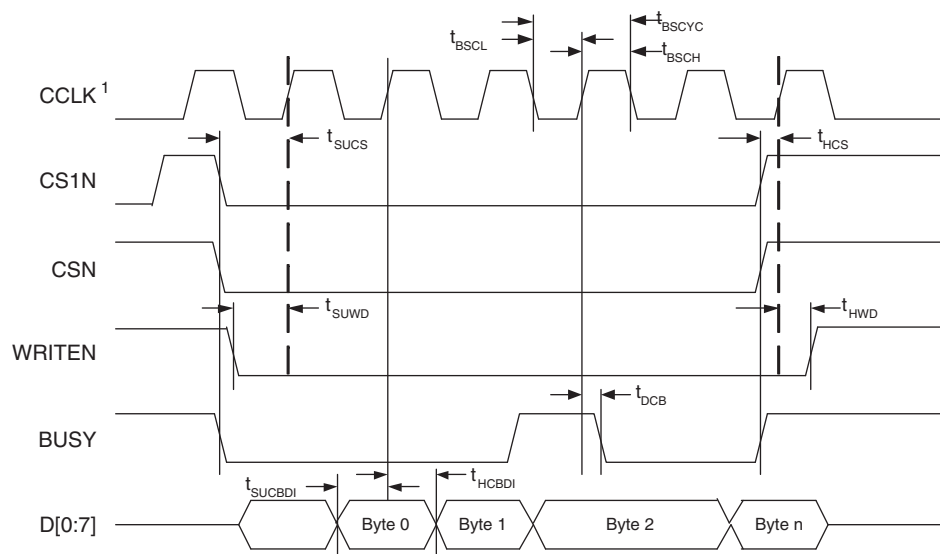
Parameter	Description	Min.	Typ.	Max.	Units
sysCONFIG Byte Data Flow					
t_{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7		—	ns
$t_{HCB DI}$	Byte D[0:7] Hold Time to CCLK	1		—	ns
t_{CODO}	Clock to Dout in Flowthrough Mode	—		12	ns
t_{SUCS}	CS[0:1] Setup Time to CCLK	7		—	ns
t_{HCS}	CS[0:1] Hold Time to CCLK	1		—	ns
t_{SUWD}	Write Signal Setup Time to CCLK	7		—	ns
t_{HWD}	Write Signal Hold Time to CCLK	1		—	ns
t_{DCB}	CCLK to BUSY Delay Time	—		12	ns
t_{CORD}	Clock to Out for Read Data	—		12	ns
sysCONFIG Byte Slave Clocking					
t_{BSCH}	Byte Slave Clock Minimum High Pulse	6		—	ns
t_{BSCL}	Byte Slave Clock Minimum Low Pulse	9		—	ns
t_{BSCYC}	Byte Slave Clock Cycle Time	15		—	ns
t_{SUSCDI}	Din Setup time to CCLK Slave Mode	7		—	ns
t_{HSCDI}	Din Hold Time to CCLK Slave Mode	1		—	ns
t_{CODO}	Clock to Dout in Flowthrough Mode	—		12	ns
sysCONFIG Serial (Bit) Data Flow					
t_{SUMCDI}	Din Setup time to CCLK Master Mode	7		—	ns
$t_{HMC DI}$	Din Hold Time to CCLK Master Mode	1		—	ns
sysCONFIG Serial Slave Clocking					
t_{SSCH}	Serial Slave Clock Minimum High Pulse	6		—	ns
t_{SSCL}	Serial Slave Clock Minimum Low Pulse	6		—	ns
sysCONFIG POR, Initialization and Wake Up					
t_{ICFG}	Minimum Vcc to INIT High	—		50	ms
t_{VMC}	Time from t_{ICFG} to Valid Master Clock	—		2	us
t_{PRGMRJ}	Program Pin Pulse Rejection	—		8	ns
t_{PRGM}	PROGRAMN Low Time to Start Configuration	25		—	ns
t_{DINIT}	INIT Low Time	—		1	ms
$t_{DPPINIT}$	Delay Time from PROGRAMN Low to INIT Low	—		37	ns
t_{DINITD}	Delay Time from PROGRAMN Low to DONE Low	—		37	ns
t_{IODISS}	User I/O Disable from PROGRAMN Low	—		35	ns
t_{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake Up Sequence	—		25	ns
t_{MWC}	Additional Wake Master Clock Signals after Done Pin High	120		—	cycles
t_{SUCFG}	CFG to INITN Setup Time	100		—	ns
t_{HCFG}	CFG to INITN Hold Time	100		—	ns
sysCONFIG SPI Port					
t_{CFGX}	Init High to CCLK Low	—		80	ns
t_{CSSPI}	Init High to CSSPIN Low	—		2	us
t_{CSCCLK}	CCLK Low Before CSSPIN Low	0		-	ns
t_{SOCDO}	CCLK Low to Output Valid	—		15	ns

Figure 3-12. sysCONFIG Parallel Port Read Cycle



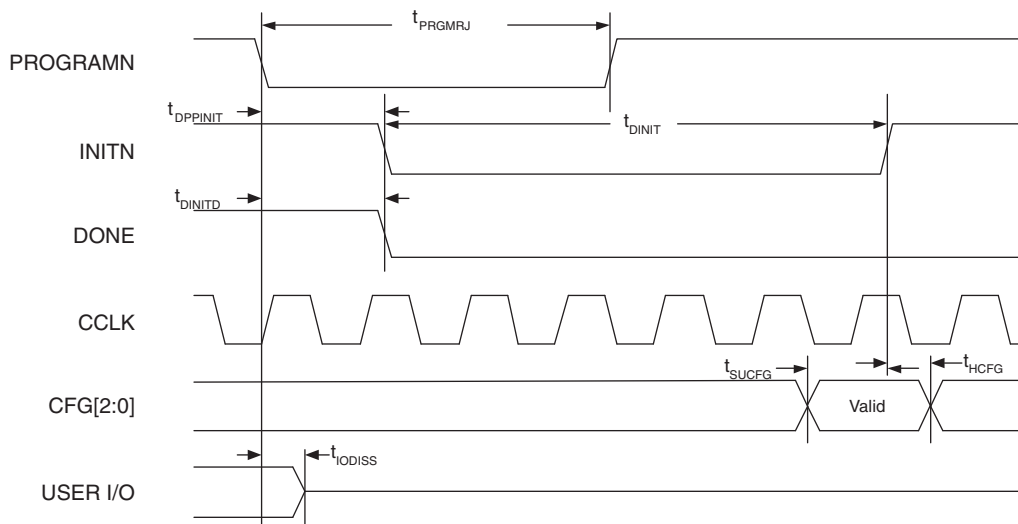
1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-13. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-17. Configuration from PROGRAMN Timing



1. The CFG pins are normally static (hard wired)

Figure 3-18. Wake-Up Timing

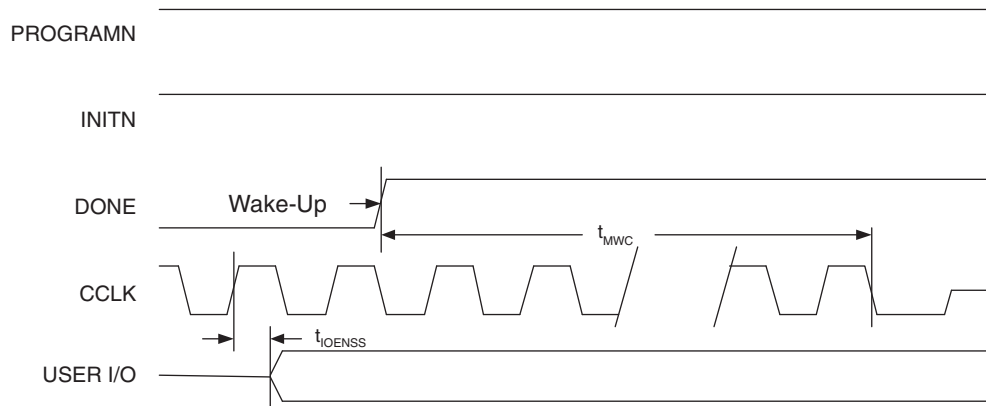
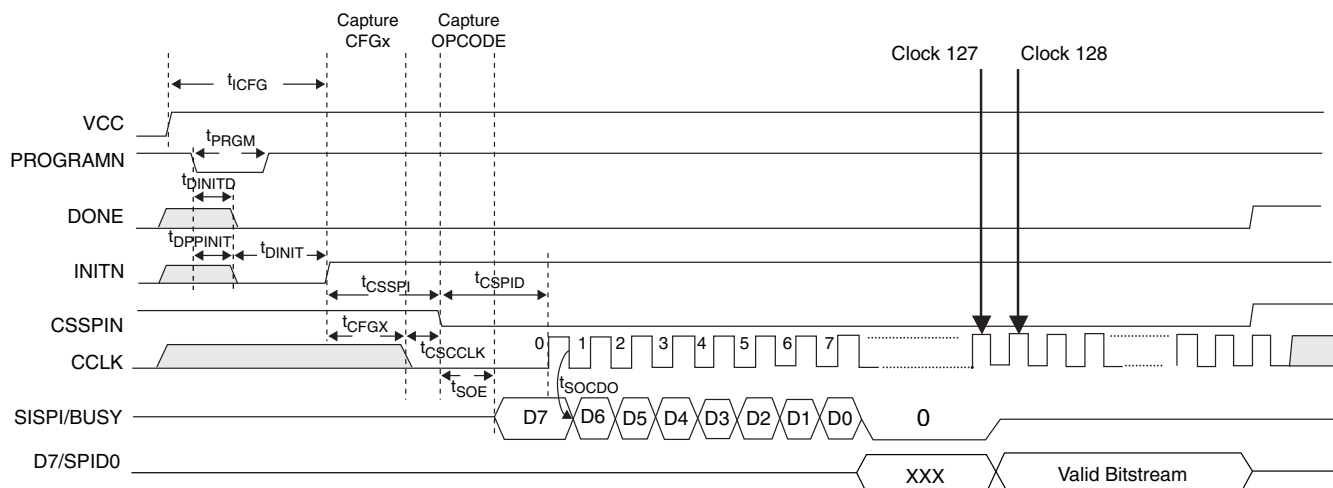


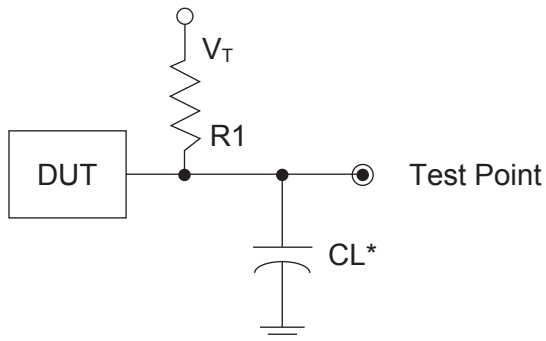
Figure 3-19. sysCONFIG SPI Port Sequence



Switching Test Conditions

Figure 3-21 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-6.

Figure 3-21. Output Test Load, LVTTTL and LVCMOS Standards



*CL Includes Test Fixture and Probe Capacitance

Table 3-6. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188 $\frac{3}{4}$	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			$V_{OH} - 0.15$	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			$V_{OL} + 0.15$	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Power Supply and NC Connections

Signals	100 TQFP	144 TQFP	208 PQFP	256 fpBGA
VCC	12, 64	EC1, EC3: 13, 92, 99 ECP/EC6: 11, 13, 92, 99	EC1, EC3: 26, 128, 135 ECP/EC6: 24, 26, 128, 135 ECP/EC10: 5, 24, 26, 128, 135, 152	E12, E5, E8, M12, M5, M9, F6, F11, L11, L6
VCCIO0	100	136, 143	EC1: 187, 208 EC3, ECP/EC6, ECP/EC10: 187, 197, 208	F7, F8
VCCIO1	86	110, 125	157, 176	F9, F10
VCCIO2	73	108	EC1: 155 EC3, ECP/EC6, ECP/EC10: 145, 155	G11, H11
VCCIO3	56	73, 84	106, 120	J11, K11
VCCIO4	38	55, 71	85, 104	L9, L10
VCCIO5	26	38, 44	EC1: 53, 74 EC2, ECP/EC6, ECP/EC10: 53, 64, 74	L7, L8
VCCIO6	24	24, 36	37, 51	J6, K6
VCCIO7	2	1	EC1: 2 EC3, ECP/EC6, ECP/EC10: 2, 13	G6, H6
VCCJ	18	19	32	L4
VCCAUX	37, 87	54, 126	EC1: 84, 177 EC3, ECP/EC6, ECP/EC10: 22, 84, 136, 177	B15, R2
VCCPLL	—	—	—	—
GND, GND0-GND7	1, 14, 25, 35, 51, 68, 74, 89	EC1, EC3: 15, 28, 37, 52, 63, 72, 80, 96, 98, 109, 117, 128, 144 ECP/EC6: 12, 15, 28, 37, 52, 63, 72, 80, 96, 98, 109, 117, 128, 144	EC1: 1, 28, 41, 52, 82, 93, 105, 116, 132, 134, 156, 168, 179 EC3: 1, 28, 41, 52, 72, 82, 93, 105, 116, 132, 134, 138, 156, 168, 179, 189 ECP/EC6: 1, 18, 25, 28, 41, 52, 72, 82, 93, 105, 116, 132, 134, 138, 156, 168, 179, 189 ECP/EC10: 1, 6, 18, 25, 28, 41, 52, 72, 82, 93, 105, 116, 132, 134, 138, 151, 156, 168, 179, 189	A1, A16, G10, G7, G8, G9, H10, H7, H8, H9, J10, J7, J8, J9, K10, K7, K8, K9, T1, T16
NC	—	EC1, EC3: 11, 12 ECP6/EC6: None	EC1: 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 18, 22, 24, 25, 54, 55, 56, 57, 58, 59, 60, 61, 62, 63, 64, 72, 103, 136, 138, 144, 145, 146, 147, 148, 149, 150, 151, 152, 158, 189, 197, 198, 199, 200, 201, 202, 203, 204, 205, 206, 207 EC3: 5, 6, 18, 24, 25, 103, 151, 152, 158 ECP/EC6: 5, 6, 151, 152 ECP/EC10: None	EC3: G5, H5, F2, F1, H4, H3, G2, G1, J4, J3, J5, K5, H2, H1, J2, J1, R12, H16, H15, G16, G15, K12, J12, J14, J15, F16, F15, J13, H13, H14, G14, E16, E15, B13, C13 ECP/EC10: None ECP/EC15: None

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
GND	GND5	5			GND5	5		
T9	PB13B	5	C		PB13B	5	C	
P8	PB14A	5	T	BDQS14	PB14A	5	T	BDQS14
N8	PB14B	5	C		PB14B	5	C	
R9	PB15A	5	T		PB15A	5	T	
R10	PB15B	5	C		PB15B	5	C	
P9	PB16A	5	T	VREF2_5	PB16A	5	T	VREF2_5
N9	PB16B	5	C	VREF1_5	PB16B	5	C	VREF1_5
T10	PB17A	5	T	PCLKT5_0	PB17A	5	T	PCLKT5_0
GND	GND5	5			GND5	5		
T11	PB17B	5	C	PCLKC5_0	PB17B	5	C	PCLKC5_0
T12	PB18A	4	T	WRITEN	PB18A	4	T	WRITEN
T13	PB18B	4	C	CS1N	PB18B	4	C	CS1N
P10	PB19A	4	T	VREF1_4	PB19A	4	T	VREF1_4
N10	PB19B	4	C	CSN	PB19B	4	C	CSN
T14	PB20A	4	T	VREF2_4	PB20A	4	T	VREF2_4
T15	PB20B	4	C	D0/SPID7	PB20B	4	C	D0/SPID7
M10	PB21A	4	T	D2/SPID5	PB21A	4	T	D2/SPID5
GND	GND4	4			GND4	4		
M11	PB21B	4	C	D1/SPID6	PB21B	4	C	D1/SPID6
R11	PB22A	4	T	BDQS22	PB22A	4	T	BDQS22
P11	PB22B	4	C	D3/SPID4	PB22B	4	C	D3/SPID4
R13	PB23A	4	T		PB23A	4	T	
R14	PB23B	4	C	D4/SPID3	PB23B	4	C	D4/SPID3
P12	PB24A	4	T		PB24A	4	T	
P13	PB24B	4	C	D5/SPID2	PB24B	4	C	D5/SPID2
N11	PB25A	4	T		PB25A	4	T	
-	-	-			GND4	4		
N12	PB25B	4	C	D6/SPID1	PB25B	4	C	D6/SPID1
R12	NC	-			PB26A	4		
GND	GND4	4			GND4	4		
-	-	-			GND4	4		
GND	GND3	3			GND3	3		
N13	PR18B	3	C	VREF2_3	PR27B	3	C	VREF2_3
N14	PR18A	3	T	VREF1_3	PR27A	3	T	VREF1_3
P14	PR17B	3	C		PR26B	3	C	
P15	PR17A	3	T		PR26A	3	T	
R15	PR16B	3	C		PR25B	3	C	
R16	PR16A	3	T		PR25A	3	T	
M13	PR15B	3	C		PR24B	3	C	
M14	PR15A	3	T	RDQS15	PR24A	3	T	RDQS24
P16	PR14B	3	C	RLM0_PLLC_FB_A	PR23B	3	C	RLM0_PLLC_FB_A
GND	GND3	3			GND3	3		

LFECP/EC10 and LFECP/EC15 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFECP10/LFEC10				LFECP15/LFEC15			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
N7	PB18B	5	C		PB18B	5	C	
R7	PB19A	5	T		PB19A	5	T	
R8	PB19B	5	C		PB19B	5	C	
M7	PB20A	5	T		PB20A	5	T	
M8	PB20B	5	C		PB20B	5	C	
T8	PB21A	5	T		PB21A	5	T	
GND	GND5	5			GND5	5		
T9	PB21B	5	C		PB21B	5	C	
P8	PB22A	5	T	BDQS22	PB22A	5	T	BDQS22
N8	PB22B	5	C		PB22B	5	C	
R9	PB23A	5	T		PB23A	5	T	
R10	PB23B	5	C		PB23B	5	C	
P9	PB24A	5	T	VREF2_5	PB24A	5	T	VREF2_5
N9	PB24B	5	C	VREF1_5	PB24B	5	C	VREF1_5
T10	PB25A	5	T	PCLKT5_0	PB25A	5	T	PCLKT5_0
GND	GND5	5			GND5	5		
T11	PB25B	5	C	PCLKC5_0	PB25B	5	C	PCLKC5_0
T12	PB26A	4	T	WRITEN	PB26A	4	T	WRITEN
T13	PB26B	4	C	CS1N	PB26B	4	C	CS1N
P10	PB27A	4	T	VREF1_4	PB27A	4	T	VREF1_4
N10	PB27B	4	C	CSN	PB27B	4	C	CSN
T14	PB28A	4	T	VREF2_4	PB28A	4	T	VREF2_4
T15	PB28B	4	C	D0/SPID7	PB28B	4	C	D0/SPID7
M10	PB29A	4	T	D2/SPID5	PB29A	4	T	D2/SPID5
GND	GND4	4			GND4	4		
M11	PB29B	4	C	D1/SPID6	PB29B	4	C	D1/SPID6
R11	PB30A	4	T	BDQS30	PB30A	4	T	BDQS30
P11	PB30B	4	C	D3/SPID4	PB30B	4	C	D3/SPID4
R13	PB31A	4	T		PB31A	4	T	
R14	PB31B	4	C	D4/SPID3	PB31B	4	C	D4/SPID3
P12	PB32A	4	T		PB32A	4	T	
P13	PB32B	4	C	D5/SPID2	PB32B	4	C	D5/SPID2
N11	PB33A	4	T		PB33A	4	T	
GND	GND4	4			GND4	4		
N12	PB33B	4	C	D6/SPID1	PB33B	4	C	D6/SPID1
R12	PB34A	4			PB34A	4		
GND	GND4	4			GND4	4		
GND	GND4	4			GND4	4		
-	-	-			GND4	4		
-	-	-			GND4	4		
GND	GND3	3			GND3	3		
N13	PR36B	3	C	VREF2_3	PR44B	3	C	VREF2_3
N14	PR36A	3	T	VREF1_3	PR44A	3	T	VREF1_3

LFEC6/EC6, LFEC6/EC10, LFEC6/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC6/LFEC6					LFEC10/LFEC10					LFEC6/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
N22	PR17A	3	T		N22	PR26A	3	T		N22	PR30A	3	T	
N19	PR16B	3	C		N19	PR25B	3	C		N19	PR29B	3	C	
N18	PR16A	3	T		N18	PR25A	3	T		N18	PR29A	3	T	
M21	PR15B	3	C		M21	PR24B	3	C		M21	PR28B	3	C	
L20	PR15A	3	T	RDQS15	L20	PR24A	3	T	RDQS24	L20	PR28A	3	T	RDQS28
L21	PR14B	3	C		L21	PR23B	3	C		L21	PR27B	3	C	
GND	GND3	3			GND	GND3	3			GND	GND3	3		
M20	PR14A	3	T		M20	PR23A	3	T		M20	PR27A	3	T	
M18	PR13B	3	C		M18	PR22B	3	C		M18	PR26B	3	C	
M19	PR13A	3	T		M19	PR22A	3	T		M19	PR26A	3	T	
M22	PR12B	3	C		M22	PR21B	3	C		M22	PR25B	3	C	
L22	PR12A	3	T		L22	PR21A	3	T		L22	PR25A	3	T	
K22	PR11B	3	C		K22	PR20B	3	C		K22	PR24B	3	C	
K21	PR11A	3	T		K21	PR20A	3	T		K21	PR24A	3	T	
J22	PR9B	2	C	PCLKC2_0	J22	PR18B	2	C	PCLKC2_0	J22	PR22B	2	C	PCLKC2_0
GND	GND2	2			GND	GND2	2			GND	GND2	2		
J21	PR9A	2	T	PCLKT2_0	J21	PR18A	2	T	PCLKT2_0	J21	PR22A	2	T	PCLKT2_0
H22	PR8B	2	C		H22	PR17B	2	C		H22	PR21B	2	C	
H21	PR8A	2	T		H21	PR17A	2	T		H21	PR21A	2	T	
L19	PR7B	2	C		L19	PR16B	2	C		L19	PR20B	2	C	
L18	PR7A	2	T		L18	PR16A	2	T		L18	PR20A	2	T	
K20	PR6B	2	C		K20	PR15B	2	C		K20	PR19B	2	C	
J20	PR6A	2	T	RDQS6	J20	PR15A	2	T	RDQS15	J20	PR19A	2	T	RDQS19
K19	PR5B	2	C		K19	PR14B	2	C		K19	PR18B	2	C	
GND	-	-			GND	GND2	2			GND	GND2	2		
K18	PR5A	2	T		K18	PR14A	2	T		K18	PR18A	2	T	
G22	PR4B	2	C		G22	PR13B	2	C		G22	PR17B	2	C	
F22	PR4A	2	T		F22	PR13A	2	T		F22	PR17A	2	T	
F21	PR3B	2	C		F21	PR12B	2	C		F21	PR16B	2	C	
E22	PR3A	2	T		E22	PR12A	2	T		E22	PR16A	2	T	
E21	NC	-			E21	PR11B	2	C		E21	PR15B	2	C	
D22	NC	-			D22	PR11A	2	T		D22	PR15A	2	T	
G21	NC	-			G21	NC	-			G21	PR14B	2	C	
G20	NC	-			G20	NC	-			GND	GND2	2		
GND	-	-			-	-	-			G20	PR14A	2	T	
J18	NC	-			J18	NC	-			J18	PR13B	2	C	
H19	NC	-			H19	NC	-			H19	PR13A	2	T	
J19	NC	-			J19	NC	-			J19	PR12B	2	C	
H20	NC	-			H20	NC	-			H20	PR12A	2	T	
H17	NC	-			H17	NC	-			H17	PR11B	2	C	
H18	NC	-			H18	NC	-			H18	PR11A	2	T	
D21	NC	-			D21	PR9B	2	C	RUM0_PLLC_FB_A	D21	PR9B	2	C	RUM0_PLLC_FB_A
GND	-	-			GND	GND2	2			GND	GND2	2		
C22	NC	-			C22	PR9A	2	T	RUM0_PLT_FB_A	C22	PR9A	2	T	RUM0_PLT_FB_A
G19	NC	-			G19	PR8B	2	C	RUM0_PLLC_IN_A	G19	PR8B	2	C	RUM0_PLLC_IN_A
G18	NC	-			G18	PR8A	2	T	RUM0_PLT_IN_A	G18	PR8A	2	T	RUM0_PLT_IN_A
F20	NC	-			F20	PR7B	2	C		F20	PR7B	2	C	
F19	NC	-			F19	PR7A	2	T		F19	PR7A	2	T	
E20	NC	-			E20	PR6B	2	C		E20	PR6B	2	C	
D20	NC	-			D20	PR6A	2	T	RDQS6	D20	PR6A	2	T	RDQS6

LFEC6/EC6, LFEC6/EC10, LFEC6/EC15 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC6/LFEC6					LFEC10/LFEC10					LFEC6/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
A4	NC	-			A4	PT9B	0	C		A4	PT9B	0	C	
B4	NC	-			B4	PT9A	0	T		B4	PT9A	0	T	
C4	NC	-			C4	PT8B	0	C		C4	PT8B	0	C	
C5	NC	-			C5	PT8A	0	T		C5	PT8A	0	T	
D6	NC	-			D6	PT7B	0	C		D6	PT7B	0	C	
B5	NC	-			B5	PT7A	0	T		B5	PT7A	0	T	
E6	NC	-			E6	PT6B	0	C		E6	PT6B	0	C	
C6	NC	-			C6	PT6A	0	T	TDQS6	C6	PT6A	0	T	TDQS6
A3	NC	-			A3	PT5B	0	C		A3	PT5B	0	C	
B3	NC	-			B3	PT5A	0	T		B3	PT5A	0	T	
F6	NC	-			F6	PT4B	0	C		F6	PT4B	0	C	
D5	NC	-			D5	PT4A	0	T		D5	PT4A	0	T	
F7	NC	-			F7	PT3B	0	C		F7	PT3B	0	C	
E8	NC	-			E8	PT3A	0	T		E8	PT3A	0	T	
G6	NC	-			G6	PT2B	0	C		G6	PT2B	0	C	
E7	NC	-			E7	PT2A	0	T		E7	PT2A	0	T	
GND	-	-			GND	GND0	0			GND	GND0	0		
A1	GND	-			A1	GND	-			A1	GND	-		
A22	GND	-			A22	GND	-			A22	GND	-		
AB1	GND	-			AB1	GND	-			AB1	GND	-		
AB22	GND	-			AB22	GND	-			AB22	GND	-		
H15	GND	-			H15	GND	-			H15	GND	-		
H8	GND	-			H8	GND	-			H8	GND	-		
J10	GND	-			J10	GND	-			J10	GND	-		
J11	GND	-			J11	GND	-			J11	GND	-		
J12	GND	-			J12	GND	-			J12	GND	-		
J13	GND	-			J13	GND	-			J13	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
J9	GND	-			J9	GND	-			J9	GND	-		
K10	GND	-			K10	GND	-			K10	GND	-		
K11	GND	-			K11	GND	-			K11	GND	-		
K12	GND	-			K12	GND	-			K12	GND	-		
K13	GND	-			K13	GND	-			K13	GND	-		
K14	GND	-			K14	GND	-			K14	GND	-		
K9	GND	-			K9	GND	-			K9	GND	-		
L10	GND	-			L10	GND	-			L10	GND	-		
L11	GND	-			L11	GND	-			L11	GND	-		
L12	GND	-			L12	GND	-			L12	GND	-		
L13	GND	-			L13	GND	-			L13	GND	-		
L14	GND	-			L14	GND	-			L14	GND	-		
L9	GND	-			L9	GND	-			L9	GND	-		
M10	GND	-			M10	GND	-			M10	GND	-		
M11	GND	-			M11	GND	-			M11	GND	-		
M12	GND	-			M12	GND	-			M12	GND	-		
M13	GND	-			M13	GND	-			M13	GND	-		
M14	GND	-			M14	GND	-			M14	GND	-		
M9	GND	-			M9	GND	-			M9	GND	-		
N10	GND	-			N10	GND	-			N10	GND	-		
N11	GND	-			N11	GND	-			N11	GND	-		
N12	GND	-			N12	GND	-			N12	GND	-		

LFEC20/EC20 and LFEC20/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC20/LFEC20					LFEC20/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
U9	PB20B	5	C		U9	PB20B	5	C	
Y8	PB21A	5	T		Y8	PB21A	5	T	
GND	GND5	5			GND	GND5	5		
Y9	PB21B	5	C		Y9	PB21B	5	C	
V9	PB22A	5	T	BDQS22	V9	PB22A	5	T	BDQS22
T9	PB22B	5	C		T9	PB22B	5	C	
W10	PB23A	5	T		W10	PB23A	5	T	
U10	PB23B	5	C		U10	PB23B	5	C	
V10	PB24A	5	T		V10	PB24A	5	T	
T10	PB24B	5	C		T10	PB24B	5	C	
AA6	PB25A	5	T		AA6	PB25A	5	T	
GND	GND5	5			GND	GND5	5		
AB5	PB25B	5	C		AB5	PB25B	5	C	
AA8	PB26A	5	T		AA8	PB26A	5	T	
AA7	PB26B	5	C		AA7	PB26B	5	C	
AB6	PB27A	5	T		AB6	PB27A	5	T	
AB7	PB27B	5	C		AB7	PB27B	5	C	
Y10	PB28A	5	T		Y10	PB28A	5	T	
W11	PB28B	5	C		W11	PB28B	5	C	
AB8	PB29A	5	T		AB8	PB29A	5	T	
GND	GND5	5			GND	GND5	5		
AB9	PB29B	5	C		AB9	PB29B	5	C	
AA10	PB30A	5	T	BDQS30	AA10	PB30A	5	T	BDQS30
AA9	PB30B	5	C		AA9	PB30B	5	C	
Y11	PB31A	5	T		Y11	PB31A	5	T	
AA11	PB31B	5	C		AA11	PB31B	5	C	
V11	PB32A	5	T	VREF2_5	V11	PB32A	5	T	VREF2_5
V12	PB32B	5	C	VREF1_5	V12	PB32B	5	C	VREF1_5
AB10	PB33A	5	T	PCLKT5_0	AB10	PB33A	5	T	PCLKT5_0
GND	GND5	5			GND	GND5	5		
AB11	PB33B	5	C	PCLKC5_0	AB11	PB33B	5	C	PCLKC5_0
Y12	PB34A	4	T	WRITEN	Y12	PB34A	4	T	WRITEN
U11	PB34B	4	C	CS1N	U11	PB34B	4	C	CS1N
W12	PB35A	4	T	VREF1_4	W12	PB35A	4	T	VREF1_4
U12	PB35B	4	C	CSN	U12	PB35B	4	C	CSN
W13	PB36A	4	T	VREF2_4	W13	PB36A	4	T	VREF2_4
U13	PB36B	4	C	D0/SPID7	U13	PB36B	4	C	D0/SPID7
AA12	PB37A	4	T	D2/SPID5	AA12	PB37A	4	T	D2/SPID5
GND	GND4	4			GND	GND4	4		
AB12	PB37B	4	C	D1/SPID6	AB12	PB37B	4	C	D1/SPID6
T13	PB38A	4	T	BDQS38	T13	PB38A	4	T	BDQS38
V13	PB38B	4	C	D3/SPID4	V13	PB38B	4	C	D3/SPID4
W14	PB39A	4	T		W14	PB39A	4	T	
U14	PB39B	4	C	D4/SPID3	U14	PB39B	4	C	D4/SPID3

Conventional Packaging
LatticeEC Commercial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC1E-3Q208C	112	-3	PQFP	208	COM	1.5K
LFEC1E-4Q208C	112	-4	PQFP	208	COM	1.5K
LFEC1E-5Q208C	112	-5	PQFP	208	COM	1.5K
LFEC1E-3T144C	97	-3	TQFP	144	COM	1.5K
LFEC1E-4T144C	97	-4	TQFP	144	COM	1.5K
LFEC1E-5T144C	97	-5	TQFP	144	COM	1.5K
LFEC1E-3T100C	67	-3	TQFP	100	COM	1.5K
LFEC1E-4T100C	67	-4	TQFP	100	COM	1.5K
LFEC1E-5T100C	67	-5	TQFP	100	COM	1.5K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC3E-3F256C	160	-3	fpBGA	256	COM	3.1K
LFEC3E-4F256C	160	-4	fpBGA	256	COM	3.1K
LFEC3E-5F256C	160	-5	fpBGA	256	COM	3.1K
LFEC3E-3Q208C	145	-3	PQFP	208	COM	3.1K
LFEC3E-4Q208C	145	-4	PQFP	208	COM	3.1K
LFEC3E-5Q208C	145	-5	PQFP	208	COM	3.1K
LFEC3E-3T144C	97	-3	TQFP	144	COM	3.1K
LFEC3E-4T144C	97	-4	TQFP	144	COM	3.1K
LFEC3E-5T144C	97	-5	TQFP	144	COM	3.1K
LFEC3E-3T100C	67	-3	TQFP	100	COM	3.1K
LFEC3E-4T100C	67	-4	TQFP	100	COM	3.1K
LFEC3E-5T100C	67	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC6E-3F484C	224	-3	fpBGA	484	COM	6.1K
LFEC6E-4F484C	224	-4	fpBGA	484	COM	6.1K
LFEC6E-5F484C	224	-5	fpBGA	484	COM	6.1K
LFEC6E-3F256C	195	-3	fpBGA	256	COM	6.1K
LFEC6E-4F256C	195	-4	fpBGA	256	COM	6.1K
LFEC6E-5F256C	195	-5	fpBGA	256	COM	6.1K
LFEC6E-3Q208C	147	-3	PQFP	208	COM	6.1K
LFEC6E-4Q208C	147	-4	PQFP	208	COM	6.1K
LFEC6E-5Q208C	147	-5	PQFP	208	COM	6.1K
LFEC6E-3T144C	97	-3	TQFP	144	COM	6.1K
LFEC6E-4T144C	97	-4	TQFP	144	COM	6.1K
LFEC6E-5T144C	97	-5	TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC10E-3F484C	288	-3	fpBGA	484	COM	10.2K
LFEC10E-4F484C	288	-4	fpBGA	484	COM	10.2K
LFEC10E-5F484C	288	-5	fpBGA	484	COM	10.2K
LFEC10E-3F256C	195	-3	fpBGA	256	COM	10.2K